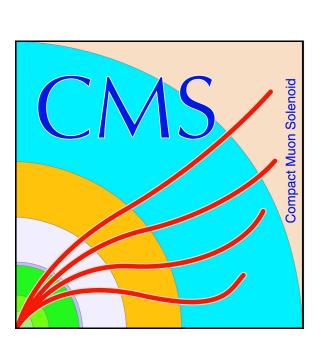
Telescope to Test CMS Pixel Upgrade Detectors



Caleb Fangmeier on behalf of the CMS Collaboration



The innermost layer of the CMS Detector at the LHC is the silicon pixel tracker. The current version of the detector has performed well and been critical to the physics program of CMS. The HL-LHC Upgrade of CMS will replace the entire silicon tracking system. As part of this upgrade, a proposed new section of the pixel tracker will be added in the so-called "very-forward" $(\eta \sim 4)$ region of the detector. Because the particles in this region are traveling almost parallel to the magnetic field of the detector, enhanced ϕ sensitivity is required to accurately measure track curvature. Therefore, the proposed detector will reshape the standard $100 \times 150 \mu$ m pixels to be more sensitive in ϕ , sacrificing precision in ρ . A telescope is being developed for the express purpose of characterizing different pixel geometries. The telescope operates by using eight layers of silicon-strip sensors, with the device-under-test placed with four on each side. A charged-particle beam is directed so it passes through both the strip sensors and the device-under-test. Measurements from the telescope are taken to reconstruct individual particle tracks. These tracks are then compared to data collected from the device-under-test to characterize its performance.

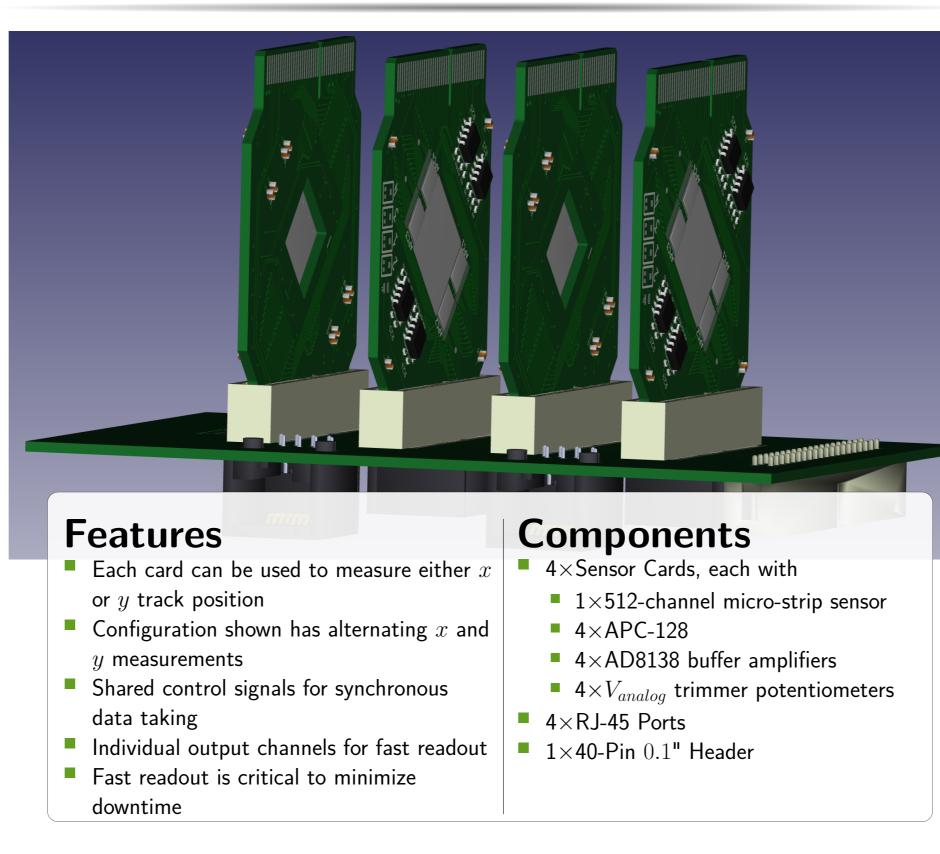
Hardware

Analog Pipeline Chip (APC-128)

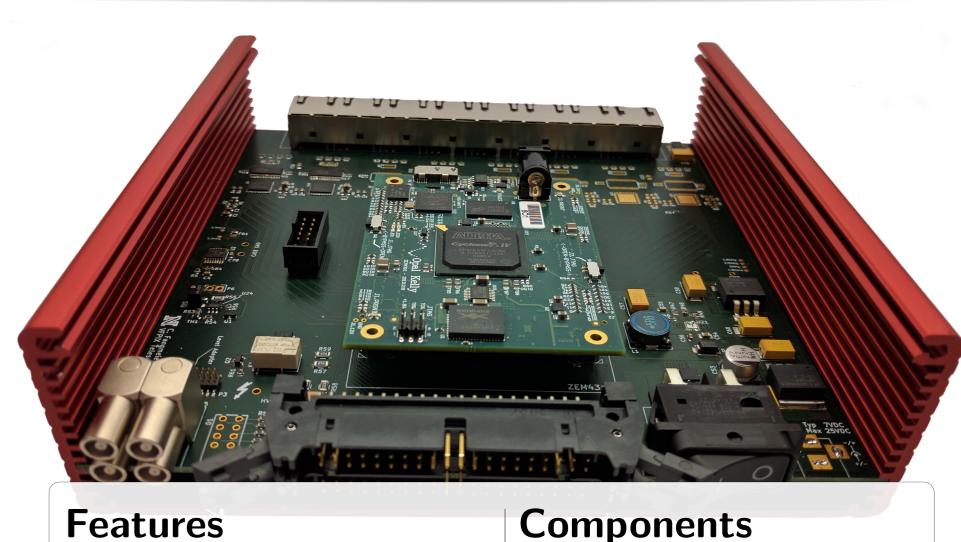
Reset -RФ1 **R**Ф2 128 channels 32 cell pipeline CAL Pipeline shift register Developed for the tracker of the H1 detector at HERA

- Serializes the analog pulse-heights of 128 channels to dramatically reduce the number of required I/O lines
- Capable of sampling waveform data from of a strip sensor at upwards of 20MHz
- Features a very good signal-to-noise ratio of 40
- Low noise combined with inter-strip charge-sharing give each layer of the detector a measurement precision of $\approx 1 \mu \text{m}$

Sensor Board



Data Acquisition (DAQ)



Features

Generates the control signals needed by

of sources via an translator mezzanine card

- the APC-128s 32 ADC Channels to read out all APC128s
- in parallel, minimizing dead time
- FPGA Board with associated USB hardware enables high-speed
- communication with online software Handles external triggering from a variety

EVENT CONSTRUCTION

TIMESTAMP: 123453234.12345

SENSOR_1_POSITION: 1.254 mm

SENSOR 2 POSITION: 6.231 mm

SENSOR_8_POSITION: 1.25 mm

EVENT START

EVENT END

- 1×Opal Kelly ZEM4310 with Cyclone IV FPGA
- 128MB RAM ■ USB-3.0
- 2×HSMC Connectors ■ 8×AD9219 40MHz/10 bit ADCs
- 8×RJ-45 Ports
- 2×40-Pin 0.1" Header Bias-voltage control relay

On-board power regulation

- TRACK RECONSTRUCTION

- PERFORMANCE MEASUREMENTS

- ALIGNMENT

OFFLINE ANALYSIS

Readout Scheme

In-Beam Electronics STRIP SENSOR OUTPUT APC-128 OUTPUT CHARGE SHARED AMONG SAMPLE POINTS

- The sensor is a silicon NP-Junction operated in "reverse-bias" mode where all free charge carriers are evacuated
- An energetic charged particle passing through the silicon deposits energy to create free electron-hole pairs which are then separated by the electric field produced by the biasing voltage
- The electrons create a current spike that the readout chip, the APC-128, samples and stores
- Upon receiving a trigger, the APC-128 serializes the analog pulse-height sample from each of the 128 channels

APC-128 Testboard



A custom board was developed for gaining familiarity with the APC-128 chip, and for testing different control and readout schemes. It features:

- 1×APC-128 (bottom of board)
- 1×RJ-45 jack for testing differential output stage
- 40-Pin header for supplying control signals
- Automatic and manual adjustment of analog reference voltages

DAQ Board

DIGITIZED PULSE-HEIGHT VALUES 18/16/14/11/19/20/16/16/17/18/16/17/23/17 17 18 17 15 16 21 50 115 59 24 18 17 14 15 17/14/15/17/17/14/16/22/12/14/13/26/20 18 19 17 17 27 23 55 112 54 15 18 16 18 19

HIT DETECTION HIT START SENSOR: 6 STRIP: 7 PULSE HEIGHT: 50 STRIP: 8 PULSE HEIGHT: 115 STRIP: 9 PULSE HEIGHT: 59 HIT END

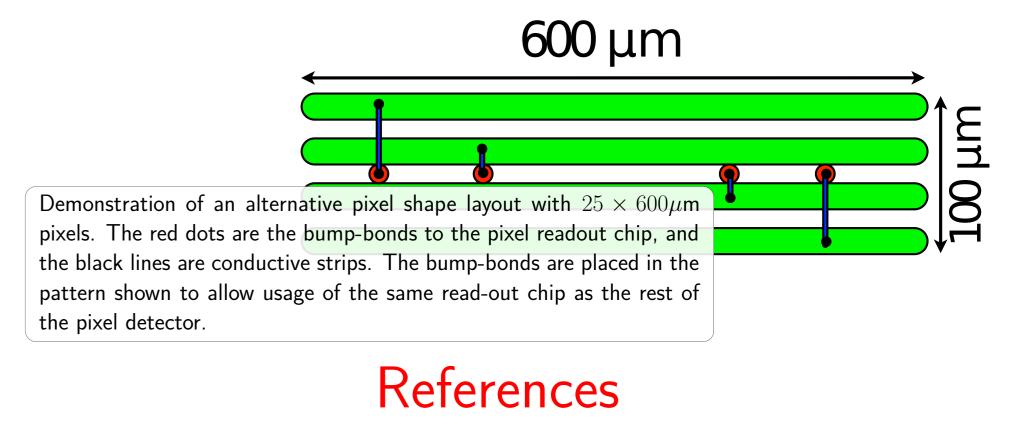
- The analog pulse-heights from the 32 APC-128s in the telescope are digitized by 8 high-speed 4-channel ADCs located on the DAQ board
- The digitized values passed to an FPGA board where they are processed into individual sensor hits
- Digitized values smaller than the noise-suppression threshold are dropped
- The sensor hit data are passed across a USB-3 connection to a PC
- Its job finished, the DAQ Board becomes idle and waits for the next trigger

Progress

- ✓ System design and parts selection
- ✓APC-128 readout chain proof of concept
- ✓ Circuit design and PCB Layout
- □ Assembly and offline testing (in progress)
- □FPGA Firmware development and testing
- □Online/Offline software development
- □Commissioning runs with UNL Diocles electron beam

Desktop PC

- Online software organizes the hits into events and stores them to disk Since the detector layers can shift in space significantly during
- operation, alignment must first be done to accurately measure the geometry of the detector
- After alignment, the various layer hits can be combined to construct extremely precise tracks
- The tracks can then be compared for consistency with the data collected in parallel from the device-under-test, and, using the telescope as the ground truth, establish performance characteristics



- "Proposal for R&D Related to the Module and Sensor Design for the Phase-2 Upgrade of the CMS Forward Pixel Detector" A. Dominguez et al. CMS Document 12163-v1
- PCB Design Files: https://github.com/cfangmeier/VFPIX-telescope-PCB
- **Software Repository** https://github.com/cfangmeier/VFPIX-telescope-Code

Acknowledgments

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